

## Device Characterization and High Throughput Testing at Temperature

- Temperature testing of analog and mixed signal devices
- Concise reports with clear analysis and conclusions
- Temperature range =  $-55^{\circ}\text{C}$  to  $200^{\circ}\text{C}$
- Data capture during temperature cycling
- Wafer and final device characterization
- Data interpretation by Ph.D. scientists and engineers
- Statistical analysis of overall trends and wafer mapping

